

PATENT5298-025027PM98019C

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re Application of:

Sethuraman et al.

Serial No. 09/779,123

Filed: February 7, 2001

For:

PLANARIZED SEMICONDUCTOR

INTERCONNECT TOPOGRAPHY AND METHOD FOR POLISHING A

METAL LAYER TO FORM

INTERCONNECT

Group Art Unit: 2823 Examiner: Lee, H.

Atty. Dkt. No. 5298-02502

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: MS: Non-Fee Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313, on the date indicated below:

August 6, 2003 Date

Pamela Ger

AMENDMENT; RESPONSE TO OFFICE ACTION DATED MAY 8, 2003

MS: Non-Fee Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313

Dear Sir/ Madam:

This paper is submitted in response to the Office Action dated May 8, 2003 to further highlight reasons why the application is in condition for allowance.

Amendments to the Specification begin on page 2 of this paper.

Remarks/Arguments begin on page 3 of this paper.